

SID

Factory: Rot am See

Article:

523

ML6

Provided:

Kracht, Enrico

Customer:

Date:

10.08.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	360		2	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		3	
		35	L2		
B-RS-FR4-ML-0.93mm-035+035-TG150-HF	50200663	930		4	A01
		35	L3		
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	345		5	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		6	B00
		35	L4		
B-RS-FR4-ML-0.93mm-035+035-TG150-HF	50200663	930		7	A02
		35	L5		
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	360		8	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		9	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	10	

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

3101 µm

Version 1.2.14.15

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